

Applic. No.: 09/436,598

Marked-Up Version of the Amended Claims:

Claim 1 (twice amended). A power semiconductor module,  
comprising:

semiconductor components and connecting elements;

a plastic housing having an interior, a flat inside, and  
[connecting element] openings formed therein, said openings  
having an inner side adjacent said interior;

a substrate disposed in said plastic housing defining a  
housing base of said plastic housing, said substrate  
containing a ceramic plate having a top side and a bottom side  
with a top metallization layer disposed on said top side and a  
bottom metallization layer disposed on said bottom side, said  
top metallization layer facing said interior of said plastic  
housing being patterned in order to form conductive  
interconnects and equipped for and receiving said  
semiconductor components and said connecting elements;

terminal elements in said plastic housing for providing  
external terminals, said terminal elements having lugs, said  
terminal elements in the region of said lugs being press-  
fitted into said [connecting element] openings in said plastic  
housing, said terminal elements bearing on said flat inside of

said plastic housing, and said lugs pressing against said  
inner side of said openings for fixing said terminal elements  
in position; and

wires bonded to said terminal elements and to said  
semiconductor components.